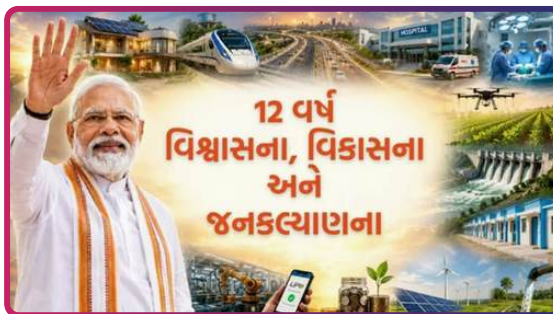




Dear Patrons,

The month of June brings another set of encouraging developments across India's semiconductor and electronics ecosystem, reflecting the growing momentum around technology, talent, and global collaboration.

Our participation in the **EU-India TTC Business Forum 2026** in New Delhi marked an important step towards strengthening India-EU collaboration in semiconductors, AI, digital infrastructure, and innovation. **IESA Chairman Navin Bishnoi** shared industry perspectives on trusted AI and compute ecosystems, while **EC Members Anand Kumar of STMicroelectronics India and Hitesh Garg of NXP**, along with member company **Infineon Technologies**, contributed to discussions around the EU-India Semiconductor Corridor.

The momentum around India's semiconductor manufacturing ambitions was further reflected in **IESA President Ashok Chandak's** participation in a special **DD News Gujarati** documentary marking 12 years of the Hon'ble Prime Minister's government. His message highlighted Gujarat's emergence as a semiconductor manufacturing leader and reinforced IESA's vision of building a complete value chain spanning design, manufacturing, advanced packaging, materials, talent, and innovation.

As the ecosystem grows, developing the right talent remains equally critical. The **IESA WFD-CIG in-person meeting** brought industry leaders and volunteers together to deliberate on future-ready workforce pathways. Chairman **Navin Bishnoi** highlighted evolving industry talent requirements, while President **Ashok Chandak** emphasised the growing need for manufacturing talent and industry-led Faculty Development Programmes. The discussions around webinars, faculty industry visits, hackathons, and skilling courses will help translate these priorities into focused initiatives.

This vision came alive through the **4th edition of the IESA Faculty Industry Visit 2026**, which brought together **20+ faculty members from 10 academic institutions** for direct engagement with leading technology organisations. Visits to **Izmo Microsystems, MiraFra Technologies, Marvell Technology India, Krypton Solutions, and NI (National Instruments), now part of Emerson**, provided valuable exposure to semiconductor packaging, VLSI design, AI-driven infrastructure, advanced manufacturing, and test and measurement technologies. Such interactions are essential to aligning academic learning with evolving industry requirements and creating opportunities for future research, internships, and partnerships.

Alongside these engagements, our **IESA Startup Mitra and Workforce Development initiatives** continued to create avenues for knowledge exchange. Together, these engagements reflect a shared commitment to strengthening India's semiconductor ecosystem through **global partnerships, industry collaboration, academic engagement, and workforce development**.



Yours Sincerely
Ashok Chandak
President, IESA



Yours Sincerely
Navin Bishnoi
Chairman, IESA

IESA Media & PR Dashboard: May Highlights

Overall Media Reach (Metric Coverage)

Total Media Stories	66
Print	33
Online	33
Electronic & Radio	03

Tier -1/ TV Media Visibility

Platform	Engagement
ET Electronics World	Exclusive interviews and interactions
ET NOW and Akashvani	Exclusive discussion

Policy & Industry Narrative

Topic	Platform
India's semiconductor roadmap, AI-driven semiconductor demand, chip design competitiveness	The Hindu Business Line, Economic Times, Forbes India, ET Edge Insights, and DQ India
AI is rewriting the memory chip industry. Can India build its own ecosystem?	Firstpost
India's Semiconductor Future Will Be Built on Trust, Not Just Chips	ET Edge Insights
Semiconductor Opportunities, Focus on designing and packaging	The Hindu, Forbes, The Times of India, Deccan Chronicle

Regional Media Impact

Focus Area	Coverage
Record global semiconductor equipment	Samaya, Amruta Dunia, Biswabani, Desbarta, Dharitri, Kalinga Mail, Mallahar, Manthan, Orissa Times, Pratigyan, Sakala, Azad Sipahi, Utkal Samaja, Swantra Barta, Divya Gujarat, Gujarat Pranam
Industry working with govt on next phase of India Semiconductor Mission; focus on supply chain, talent.	Telegana Journal, Karnataka Live, Kashmir Newslane, Rajasthan Ki Khabar, Kashmir Breaking News, Delhi Live News, Maharashtra Samachar, Bihar 24x7, South India News

Social Media Growth

Platform	Performance
LinkedIn	+527
Twitter/ X Engagement	2300+ impressions, 298 engagements, and 24 new followers

Key Highlights

- IESA's media engagement significantly strengthened policy visibility, industry credibility, collaboration, and national and regional reach, reinforcing IESA and industry partners as a trusted voice in India's ESDM and semiconductor ecosystem.

[View PR Coverage Summary](#)



IESA Strengthens India-EU Technology Collaboration at TTC Business Forum 2026

IESA partnered with the EU-India TTC Business Forum 2026 held on 4 June in New Delhi, reinforcing India-Europe collaboration in semiconductors, AI, digital infrastructure, and innovation. IESA Chairman Navin Bishnoi shared industry insights during the session on trusted AI and compute ecosystems. IESA EC Members Anand Kumar (STMicroelectronics India) and Hitesh Garg (NXP), along with member company Infineon Technologies, contributed to discussions on the EU-India Semiconductor Corridor. The forum strengthened strategic partnerships, innovation, resilient supply chains, and deeper India-EU technology cooperation.

IESA Highlights Gujarat's Leadership in India's Semiconductor Growth

IESA President Ashok Chandak shared the association's perspective in a special DD News Gujarati documentary marking 12 years of the Hon'ble Prime Minister's government. Chandak highlighted Gujarat's emergence as India's semiconductor manufacturing leader, with Micron Technology, Kaynes Semicon, and Suchi Semicon already in production, while CG SEMI is expected to commence operations soon. He emphasised that India's semiconductor journey is focused on building a complete value chain spanning design, manufacturing, advanced packaging, materials, talent, and innovation to establish India as a trusted global semiconductor partner.



[Watch Full Video](#)

IESA Represents at Make in Haryana Policy Launch



IESA Director – Government Relations and Policy, Dharmendra Singh Yadav, attended the launch of the Make in Haryana Policy and other sectoral policies organised by the Department of Industries & Commerce, Government of Haryana, on 1 June 2026 at Grand Hyatt Gurgaon. Chaired by Shri Nayab Singh Saini, Hon'ble Chief Minister of Haryana, the event featured key policy launches, announcements, MoU exchanges, and discussions aimed at strengthening Haryana's industrial and investment ecosystem. The event brought together government and industry stakeholders to explore opportunities for greater economic and sectoral growth.

IESA WFD-CIG Meeting Advances Semiconductor Workforce Development

The IESA Workforce Development – Core Initiative Group (WFD-CIG) successfully concluded its in-person meeting on 17 June, bringing together industry leaders and volunteers to strengthen India's semiconductor and electronics talent ecosystem. IESA Chairman Navin Bishnoi highlighted the evolving workforce needs and the importance of future-ready skilling pathways, while IESA President Ashok Chandak emphasised the growing demand for manufacturing talent and industry-led Faculty Development Programmes (FDPs). Discussions focused on four strategic areas—Webinars, Faculty Industry Visits, Hackathons, and Skilling Courses—with recommendations identified for action through dedicated working groups.



IESA Advocates Industry-Aligned Talent Development at Multi-Sector Industry Dialogue

On 30 June, IESA participated in the Multi-Sector Industry Dialogue on Building India's Talent Advantage, organised by FutureSkills Prime, BCG, NASSCOM, and MeitY. Representing IESA, Viswanathan K.G., Director – Workforce Development, shared industry perspectives on strengthening India's semiconductor talent pipeline. IESA emphasised expanding Faculty Development Programmes aligned with emerging semiconductor technologies and enabling structured Faculty Industry Immersion to bridge classroom learning with manufacturing realities.



IESA President Ashok Chandak Featured in Firstpost

IESA President Ashok Chandak, in a recent conversation with Firstpost, shared insights into the evolving global memory chip landscape amid surging AI demand. He highlighted how leading semiconductor manufacturers are prioritising High Bandwidth Memory (HBM) over conventional DRAM and NAND chips. Chandak noted that while front-end fabrication demands significant capital and decades of intellectual property, India is steadily building capabilities through assembly, testing, and advanced packaging. Initiatives such as Micron's Sanand plant are helping strengthen India's position in the global semiconductor supply chain.



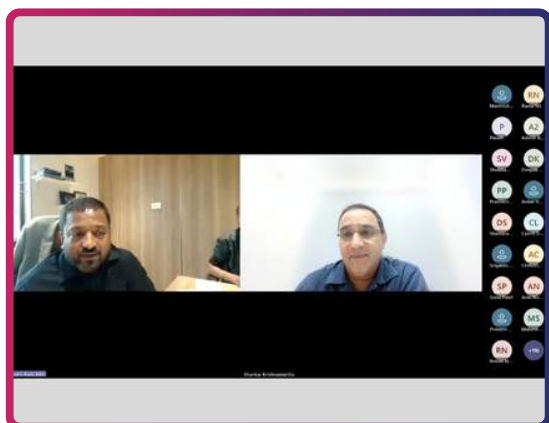
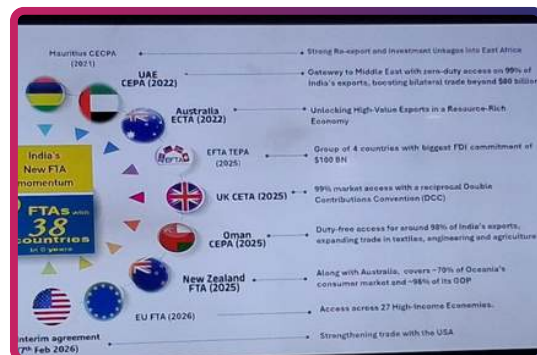
[Read the Full Article](#)

IESA Chairman Navin Bishnoi Featured in ET Telecom

IESA Chairman Navin Bishnoi, in an interaction with ET Telecom, highlighted the need for a holistic approach to India Semiconductor Mission (ISM) 2.0, focusing on building the entire semiconductor value chain. He called for policy support and incentives covering raw materials, minerals, chemicals, gases, equipment, talent, intellectual property, and startups. Bishnoi also emphasised strengthening India's domestic semiconductor design ecosystem and encouraging greater participation from both global and Indian companies to build a resilient, end-to-end semiconductor ecosystem.

IESA Participates in a Pilot Workshop on Electronics Sector

Dharmendra Singh Yadav, IESA Director - Government Relations and Policy, participated in the pilot workshop on "Leveraging FTAs for Electronics Sector", held on 5 June 2026 at Vanijya Bhawan, New Delhi. Organised by the Mobile and Electronic Devices Export Promotion Council (MEDEPC), the workshop explored effective FTA utilisation, export opportunities, Rules of Origin, compliance requirements, and strategies to enhance India's electronics export competitiveness. The programme provided valuable insights into leveraging FTAs to expand exports and strengthen market access across key international partner countries.



[Watch the Full Webinar](#)

Highlights from Karnataka ESDM Policy Outreach Program webinar

IESA Startup Mitra successfully hosted the Karnataka ESDM Policy Outreach Program webinar on 4 June, attracting over 140 attendees from the electronics, semiconductor, and deep-tech ecosystem. The session, led by Pramod L. Patil, KAS, General Manager, Karnataka Innovation and Technology Society (KITS), provided valuable insights into the Karnataka ESDM Policy, highlighting key initiatives, incentives, and opportunities available to startups, entrepreneurs, and ecosystem stakeholders across the Electronics System Design and Manufacturing (ESDM) sector. The webinar witnessed enthusiastic participation, fostering meaningful discussions on strengthening the state's technology and innovation landscape.

From Electronics Concepts to Automotive Applications: Key Insights from IESA Webinar

25 June 2026, Mr R. Saravanan, Technologist - Automotive & Semiconductor Business, Automotive Robotics Inc., led an insightful IESA Workforce Development Webinar on the topic "Theory to Wheels: Bridging Electronics Concepts and Automotive Applications (A Case Study Approach)". Exploring how electronics fundamentals translate into real-world automotive applications. Through a practical, case study-driven approach, the session offered participants valuable perspectives on embedded electronics, semiconductor integration, and AI-powered vehicle architectures.

Workforce Development Webinar

Theory to Wheels: Bridging Electronics Concepts and Automotive Applications
(A Case Study Approach)

MR. R. SARAVANAN
Automotive Robotics Inc.
Technologist - Automotive & Semiconductor Business

Academic Engagements

Highlights from the 4th Edition of the IESA's 3 Days Faculty Industry Visit 2026

Led by Viswanathan K.G., Director – Workforce Development, IESA, the 4th edition of the IESA Faculty Industry Visit 2026 brought together 20+ faculty members from 10 academic institutions for a three-day industry immersion programme. The visit provided valuable exposure to cutting-edge semiconductor technologies while strengthening academia-industry collaboration and fostering greater understanding of evolving industry practices.

Day 1: Faculty members visited Izmo Microsystems, gaining insights into System-in-Package (SiP), silicon photonics, RF assemblies, and EV power modules. The second engagement at Mirafra Technologies provided exposure to VLSI and silicon design, including RTL design, verification, silicon validation, and physical design.

Day 2: At Marvell Technology India, faculty explored semiconductor technologies across compute, connectivity, and storage, particularly those supporting AI and next-generation data infrastructure. The visit to Krypton Solutions offered first-hand exposure to high-precision contract manufacturing through a presentation and lab visit.

Day 3: The programme concluded with a visit to NI, where faculty gained insights into automated test and measurement technologies and their applications across semiconductor and industrial sectors. The engagement further strengthened academia-industry collaboration and opened avenues for future research, internships, and partnerships.

The three-day programme brought together everyone, resulting in stronger industry-academia collaboration, discussions on joint research, internships, curriculum alignment, and future strategic partnerships. Participating organisations and faculty members were felicitated in recognition of their valuable contributions.



UPCOMING EVENTS

- SEMICON India Hackathon 2026- 24 July

StartUp / MSMEs of the Month - June 2026



Company Name: MSP & Technologies Pvt. Ltd.

Location: Theni, Tamil Nadu

Founder : Dr. Murugeswaran Suruliveli

Website: <http://www.mspand.com>

Email ID: contact@mspand.com

Overview:

MSPAND Technologies Private Limited, founded in 2014 and headquartered in Theni, Tamil Nadu, India, is a rapidly growing technology company specializing in semiconductor engineering and software development solutions. With deep expertise in VLSI design and verification, custom software services, and digital innovation, MSPAND serves as a reliable partner for clients across industries. Leveraging decades of combined experience across the most demanding technology sectors in the semiconductor field, MSPAND has become a growth hub for both budding engineers and industry professionals. The company is firmly established in front-end and back-end VLSI domains, as well as modern IT and software technologies, offering a full spectrum of solutions to meet client needs.

Key Products/ Services/ Highlight:

BIOFINOUT: Managing and tracking your employee status with our biometric system with Wi-Fi connectivity. Battery backup and cloud sync to prevent data loss and ensure business continuity.

ORDER MANAGEMENT SYSTEM: App to optimize Retail operations, designed to optimise inventory management, streamline order processing. End-to-end visibility by providing real-time updates to both the retailer and the customer. Monitoring your order from placement to delivery.

Human Resource Management (HRMS):

Streamline your work management with our all-in-one HRMS, from onboarding to payroll and attendance in Biometric system with Wi-Fi connectivity.

MSPAND Switch: Turning the normal device to IoT model. Control your devices from anywhere with seamless Wi-Fi connectivity and easily manage and control connected devices with built-in relay support

Services

DFT & Test Solutions: Comprehensive DFT methodologies to ensure high yield and reliability in modern semiconductor manufacturing.

Layout Design: Specialized in ultra-low power designs and high-performance processor cores for enterprise computing.

Embedded and IoT Solutions: End-to-end hardware and software development for connected devices, smart systems, and edge computing applications.

Software Development: Full-stack software solutions for digital product development, deployment, and maintenance.

StartUp / MSMEs of the Month - June 2026



Company Name: Ciris Semiconductor India Pvt Ltd

Location: Hyderabad

Founder : Subhash Sachan

Website: www.cirissemi.com

Email ID: subhash.sachan@cirissemi.com

Overview:

CirisSemi is the recognized leader of silicon-proven Analog, Mixed-signal and IO design for system-on-chip (SoC). CirisSemi's design portfolio includes high-performance ADCs, DACs, PLLs, SerDes, AFE, Special IO's, Power Management Solutions (PMIC), Readout Integrated Circuit (ROIC) and various Analog and Digital building blocks.

Key Products/ Services/ Highlights:

- PMIC (DCDC Buck Converter, LDO , OPM , PoRBoR , References)
- ADC ,DAC, PLL
- SerDes 10Gbps per lane (8/16/32 bit) depth
- Analog Front End
- ROIC 640x512 ,1x512, 256x256 array
- Analog design and layout services

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